- Low Voltage Operation . . . 2.5 V to 7 V
- Low Power ... 3. 5 mA (f = 500 kHz, Duty = 50%)
- Internal Undervoltage Lockout Protection
- Internal Short Circuit Protection
- Wide Operating Frequency . . . 50 kHz to 1 MHz
- Internal Precision Reference . . . 1.25 V ±1% (25°C)
- On/Off Switch for CH1/3 Pair and Ch2 (see Function Table)
- 0 to 100% Dead Time Control
- Totem Pole Output Stage
- Smal I Package . . . 16 Pin TSSOP

description

The TPS5100 is a triple PWM control circuit, primarily designed to compose the power supply for LCD display. Each PWM channel has own error amplifier, PWM comparator, dead-time control and output driver. The trimmed voltage reference, oscillator, undervoltage lockout and short circuit protection are common for all channels.

This device includes two boost exclusive circuits (ch1,3) and a buck-boost exclusive circuit (ch2). The operating frequency is set with external resister and capacitor, and dead time is continuously adjustable form 0% to 100% duty cycle with resistive divider network. Soft start function can be implemented by adding a capacitor to dead time divider network. Two dead time control inputs are assigned for ch1,3 pair and ch2 individually and each dead time control input can be used to control on/off operation. TPS5100 can operate from 2.5 V supply voltage and ch1,3 pair and ch2 operate with reverse phase switching each other to achieve efficient operation in low power and battery powered system.

The TPS5100 is characterized for operation from -20°C to 85°C.

CONDITION		OUTPUT	
CONDITION	CH-1	CH-2	CH-3
DTC1/3 >. 0.3 V, DTC2 > 0.3 V	ON H	ON L	ON H
DTC1/3 > 0.3 V, DTC2 <. 0.2 V	ON H	OFF H	ON H
DTC1/3 < 0.2 V, DTC2 > 0.3 V	OFF L	ON L	OFF L
DTC1/3 < 0.2 V, DTC2 < 0.2 V	OFF L	OFF H	OFF L

FUNCTION TABLE

AVAILABLE OPTIONS

	PACKAGE
TA	TSSOP
	(PW)
-20°C to 85°C	TPS5100PW



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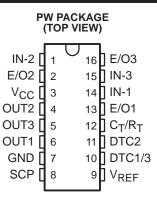
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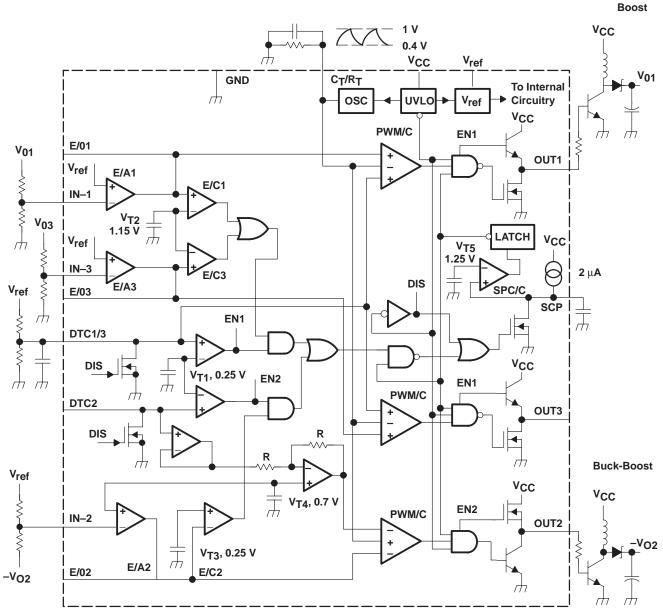
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functional block diagram



NOTE A: All voltages and currents listed are nominal.



electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V (unless otherwise noted) (see Note 1)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VREF	Reference voltage	$I_{REF} = -1 \text{ mA}, \qquad T_A = 25^{\circ}C$	1.237	1.250	1.263	V
VREF(dev)	Reference voltage change with TA	I _{REF} = -1 mA, See Note 2		15	25	mV
REGIN	Input regulation	$I_{REF} = -1 \text{ mA}, \qquad V_{CC} = 2.5 \text{ V to 7 V}$		2	5	mV
R _{EGL}	Output regulation	$I_{REF} = -0.1 \text{ mA to } -1 \text{ mA}$		1	5	mV
IOS	Short-circuit output current	$V_{REF} = 0$	-2	-10	-30	mA

NOTES: 1. Typical values of all parameters except for V_{REF(dev)} and f_{dT} are specified at T_A = 25°C.
2. The deviation parameter V_{REF(dev)} is defined as the difference between the maximum and minimum values obtained over the recommended free-air temperature range (-20°C to 85°C).

undervoltage lockout section

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VTH	Upper threshold voltage	$T_A = 25^{\circ}C$	2.2	2.3	2.4	V
V _{TL}	Lower threshold voltage	$T_A = 25^{\circ}C$	2	2.1	2.2	V
V _{hys}	Hysteresis (V _{TH} – V _{TL})	$T_A = 25^{\circ}C$	0.1	0.2	0.3	V

NOTE 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.

protection control section

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISCP	Input terminal source current		-1.4	-2	-2.6	μA
V _{T2}	Input threshold voltage	CH-1, 3	1.10	1.15	1.20	V
V _{T3}	Input theshold voltage	CH-2	0.20	0.25	0.30	v
VR	Latch reset threshold voltage	$T_A = 25^{\circ}C$	0.8	1.5		V
V _{T5}	Threshold voltage		1.20	1.25	1.30	V

NOTE 1: Typical values of all parameters except for V_{REF(dev)} and f_{dT} are specified at T_A = 25°C.

oscillator section

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
fosc	Frequency	C _T = 130 pF,	$R_T = 7 \ k\Omega$	400	500	600	kHz
fdV	Frequency change with V_{CC}	V _{CC} = 2.5 V, C _T = 130 pF,	T _A = 25°C, R _T = 7 kΩ		1%	2%	
fdT	Frequency change with TA	C _T = 130 pF,	$R_T = 7 \ k\Omega$		5%	10%	
ICT/RT	Output source current			-180	-200	-220	μΑ
VOSCH	H level output voltage			0.95	1	1.05	V
VOSCL	L level output voltage			0.35	0.40	0.45	V

NOTE 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.

dead time control section

	PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	UNIT
IBDT1/3	Input bias current	$V_{DTC1/3} = 0.35$	5 V to 1.05 V			200	nA
IBDT2	input bias current	$V_{DTC2} = 0.35$	V to 1.05 V		±2	±20	ΠA
V _{T1}	Comparator threshold voltage			0.2	0.25	0.3	V
VT0(DTC1/3)	Input threshold voltage (DTC1/3) (see Note 3)	Duty = 0%		0.3	0.4	0.5	V
VT100(DTC1/3)	input timeshold voltage (DTC1/3) (see Note 3)	Duty = 100%	f _{OSC} = 500 kHz	0.9	1	1.1	v
VT0(DTC2)	Input threshold voltage (DTC2) (see NOte 3)	Duty = 0%	fa a a 500 ki iz	0.3	0.4	0.5	V
V _{T100} (DTC2)	input theshold voltage (DTC2) (see NOte 3)	Duty = 100%	f _{OSC} = 500 kHz	0.9	1	1.1	v

NOTES: 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.

3. These specifications are not production tested. They are specified as ensured values on circuit design.



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electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3 V$ (unless otherwise noted) (see Note 1) (continued)

error amplifier section

	PARAMETER	TES	ST CONDITIONS	MIN	TYP	MAX	UNIT	
VIO	Input offset voltage	CH1, 3,	A _V = 1			15	mV	
	Input bias current	CH1, 3,	V _I =95 V to 1.55 V		±10	±20	nA	
IB	input bias current	CH2,	$V_{I} = 0.4 V \text{ to } 1 V$		±10	±20	ΠA	
Vie		CH1, 3,		0.95		1.55	V	
VIR	Input voltage range	CH2				1	v	
A _{VD}	Open-loop voltage amplification	R _{FB} = 200 k	Ω		60		dB	
В ₁	Unity-gain bandwidth				1		MHz	
V _{OM+}		V _{ID} = 0.1 V	I _O = 60 μA	1.2			V	
V _{OM} -	Output voltage swing	$v_{\text{ID}} = 0.1 v$	I _O = 0.2 mA			0.2	v	
IOM+	Output sink current	V _{ID} = 0.1 V,	V _O = 0.2 V	0.2	1		mA	
I _{OM} –	Output source current	V _{ID} = 0.1 V,	V _O = 1.2 V	-60	-100		μA	
	Input bias voltage	CH2,	$A_V = 1$, $T_A = 25^{\circ}C$	678	700	722	m)/	
V _{T4}	input bias voltage	CH2,	A _V = 1	665	700	735	735 mV	

NOTE 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.

output section

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Val	High-level output voltage	I _O = 20 mA (CH2)	2.9	3.05		V
VOH		I _O = -40 mA (CH1, 3)	1.9	2.2	2.6	v
Vai	Low-level output voltage	I _O = 20 mA (CH1, 3)		0.2	0.4	V
VOL	Low-level output voltage	I _O = 40 mA (CH2)	0.2	0.3	0.6	v
tr	Rise time	CL = 1000 pF		130		ns
tf	Fall time	I _O = 1000 pF		50		ns

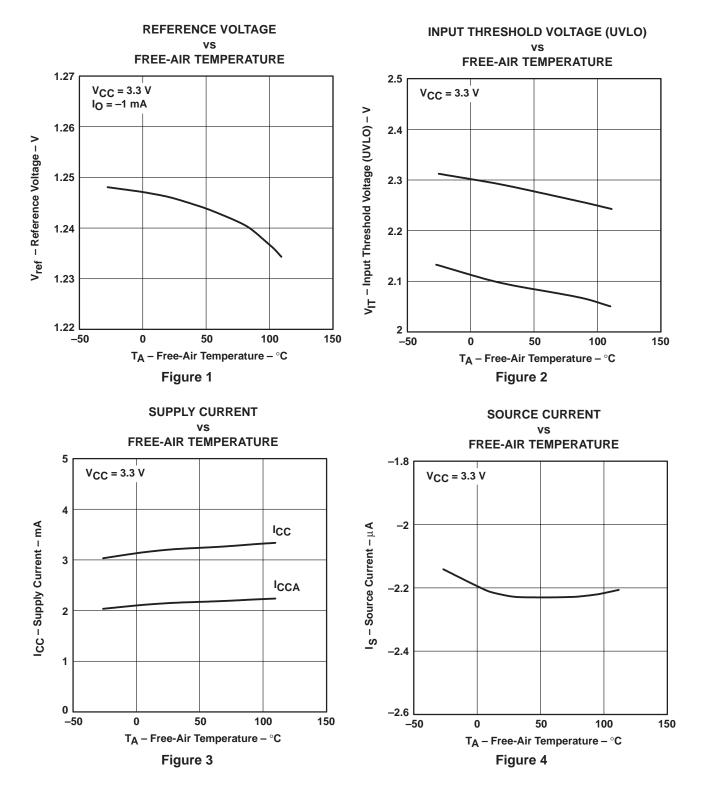
NOTE 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.

total device

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ICC	Supply current	Output OFF state		2.5	4	mA
ICCA	Average supply current	FOSC = 500 kHz, Duty = 50%, No load		3.5	5	mA

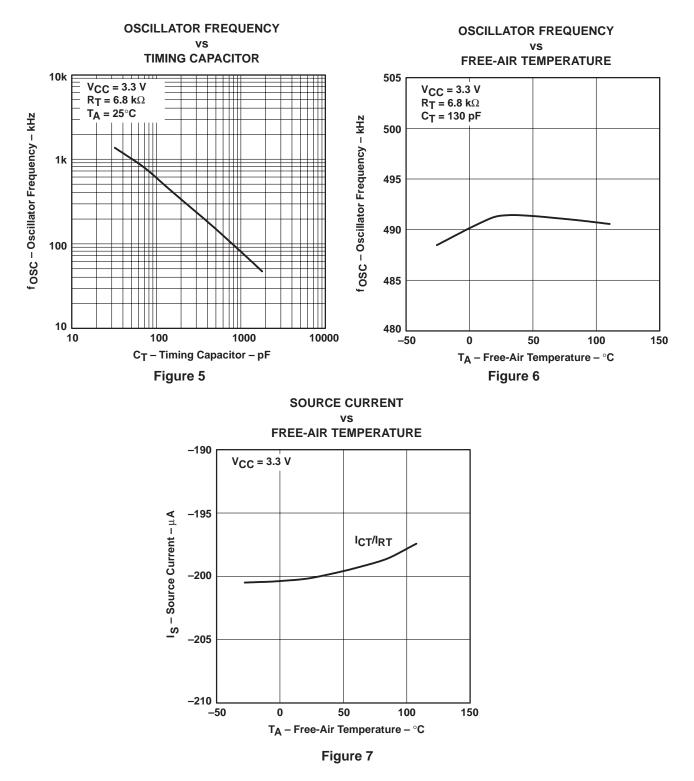
NOTE 1: Typical values of all parameters except for $V_{REF(dev)}$ and f_{dT} are specified at $T_A = 25^{\circ}C$.



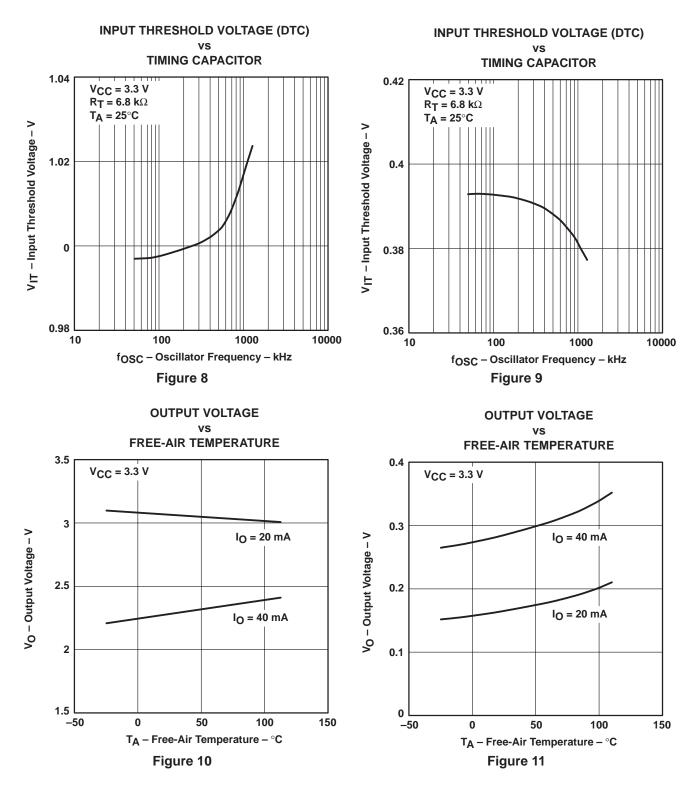




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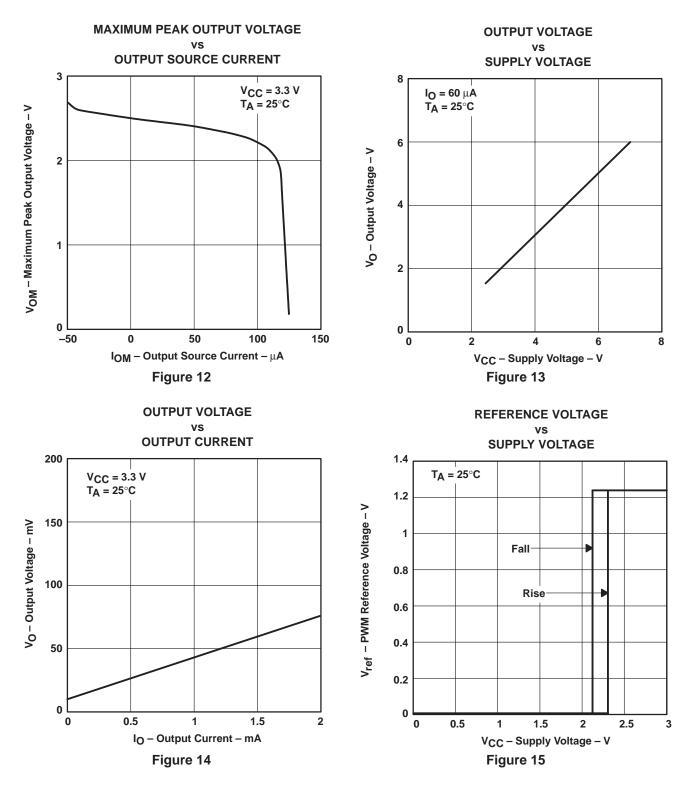




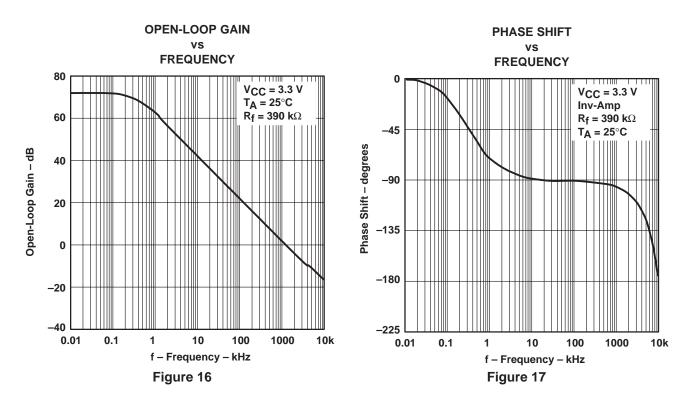




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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS5100IPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PU5100	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
TPS5100IPW	PW	TSSOP	16	90	530	10.2	3600	3.5

PW0016A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



PW0016A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0016A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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